

## P2.1 Committee on Ceramic Capacitors Minutes

Wednesday, April 28, 2010  
Hyatt Regency Grand Cypress  
Orlando, FL

### 1.0 Call to Order - Circulate Membership Roster

Meeting called to order at 11:05 am by Chairman Mike Cannon

### 2.0 Committee Organization and Procedures

2.1 Membership Intros were conducted and Roster circulated.

The attendance was as follows:

<u>NAME</u>	<u>COMPANY</u>
Michael Lauri	IBM
Mike Cannon	TDK
Christine Pollock	Presidio
Laird Macomber	CDE
Lanney McHargue (via phone)	Murata
Mary Carter Berrios	Kemet Electronics
Jayson Young	Kemet Electronics
Carl Lindquist	consultant
Ed Mikoski	ECA

A quorum was present. 6 of 9 member companies present at meeting.

<u>Member Organizations Present</u>	<u>Present at this Meeting (Spring 2010)</u>	<u>Present at the Meeting (Fall 2009)</u>	<u>Present at the Meeting (Spring 2009)</u>
AVX	N	Y	N
Cornell Dubilier	Y	Y	Y
IBM	Y	Y	Y
Kemet	Y	Y	Y
Wright Capacitor*	N	N	N
KOA Speer Electronics*	N	N	Y
SEI Electronics	N	Y	Y
TDK	Y	N	N
Vishay	Y	Y	Y
Intel*	N	N	N
KFI	Y	N	N
Murata Electronics	Y	Y	Y
<b><u>Other Organizations Present</u></b>			
ECA			

\*not in quorum calculation

**1.2 and 1.3 Approval of Agenda and Previous Minutes** – Approved Unanimously after correction to Fall 2009 meeting location.

**1.4 Review of Committee Scope** – Done with no changes

**1.5 Report on Task Groups and Committees** - Done

## **2.0 Old Business**

### **2.1 – Status of EIA-198**

**2.1.1 – Part III/3 Standard 2 terminal** – No progress under PN 5099.

**2.1.1.1 – Mechanical Outlines** – Part III/3 body sizes discussed and sent to interested members.

**2.1.2 – Part III/6 Axial PTH** – Unanimously voted to role comments into this standard. Mike Cannon to make sure the comments are included and comment resolutions are on file with Cecelia for ECA files.

**2.1.3– Part III/9 High voltage PTH & SMD** –Discussion on body sizes to be included for the SMD portion.

**2.2 – PN 4563 for test method for low inductance-** Moved to be published as a stand-alone standard. Mike Cannon to track down the status/progress with ECA. Future work has been proposed to be added to EIA 198 Section II Test Methods.

**2.3 Revision status of ANSI/EIA 521 (PN 5095)** – Mike Cannon circulated draft for all members for review and comment. This document is the next one to be finalized through this subcommittee. Time at Ceramic Working Group will be utilized to make progress.

**2.4 Five Year Review of documents** – Ed Mikoski has compiled a complete list of all committee specs and PNs for review by the committee. Group discussed getting the list into a matrix form to better coordinate/map with IEC specs. Mike Cannon / Ed Mikoski will work on coordination of this project.

**2.4.1** – EIA 198, Section 2 (Test Methods) will be reviewed by TDK and Kemet. Sent soft copy.

**2.4.2** – EIA 198, Section 3 (Individual specifications) Slash 10 Multi terminal SMD to be sent out for comments to all members.

## **3.0 New Business**

**3.1** EIA 469, rev. E –PN Status. Routed the PN form to Christine Pollock.

**3.2** EIA 595 – Discussion with IPC to harmonize spec has not happened. Ed (ECA) offered to help us with e-mail contacts at IPC and, additionally, JEITA.

## **4.0 Future Meetings** –

The next meeting Fall 2010 will be in Austin.

**5.0 Adjournment** – Meeting was adjourned at 11:57 AM

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

Michael C. Cannon

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Chairman